

<b>Notice of References Cited</b>	Application/Control No. 10/731,453		Applicant(s)/Patent Under Reexamination JOSHI ET AL.	
	Examiner David A. Zarneke		Art Unit 2891	Page 1 of 1

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*	A	US-6,461,890	10-2002	Shibata, Kazutaka	438/106
*	B	US-6,223,429	05-2001	Kaneda et al.	29/832
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	K	US-			
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	M	US-			

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**NON-PATENT DOCUMENTS**

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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.